

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC019N04LS	**Issued**	07. April 2021
MA#	MA001703550		
Package	PG-TDSON-8-46	**Weight***	118.35 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.711	0.60	0.60	6010	6010
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		319	
	non noble metal	copper	7440-50-8	37.762	31.91	31.95	319067	319482
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	378	378
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		734	
	plastics	epoxy resin	-	6.866	5.80		58013	
	inorganic material	silicondioxide	60676-86-0	36.502	30.84	36.71	308423	367170
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12266	12266
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1399	1399
solder	non noble metal	tin	7440-31-5	0.021	0.02		178	
	noble metal	silver	7440-22-4	0.026	0.02		223	
	non noble metal	lead	7439-92-1	1.008	0.85	0.89	8521	8922
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.56	9.57	95649	95774
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.84	18.87	188353	188599
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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